L	Hits	Search Text	DB	Time stamp
Number				2000/06/00
1	2124099	(integrated adj circuit) ic semiconductor	USPAT;	2002/06/28
		die chip dice	US-PGPUB;	11:07
			EPO; JPO;	
	ļ		DERWENT;	
1			IBM_TDB	
2	579735	flipchip (flip adj chip) bumps balls	USPAT;	2002/06/28
	1	standoff	US-PGPUB;	11:08
			EPO; JPO;	
			DERWENT;	}
			IBM TDB	
3	1575	257/686	USPAT;	2002/06/28
	ļ		US-PGPUB;	11:08
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
4	1 0	257/6856	USPAT;	2002/06/28
7		2377 0030	US-PGPUB;	11:08
			EPO; JPO;	11.00
			DERWENT;	
-	724	257/605	IBM_TDB	2002/06/20
5	734	257/685	USPAT;	2002/06/28
			US-PGPUB;	11:08
	1		EPO; JPO;	
			DERWENT;	
			IBM_TDB	
6	2481	257/723	USPAT;	2002/06/28
			US-PGPUB;	11:08
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
7	1398	257/777	USPAT;	2002/06/28
			US-PGPUB;	11:08
		·	EPO; JPO;	
			DERWENT;	[
		_	IBM TDB	·
8	2304	257/778	USPAT;	2002/06/28
· ·	2301	2317170	US-PGPUB;	11:08
			EPO; JPO;	11.00
			DERWENT;	
			IBM TDB	
9	1931	257/737	USPAT;	2002/06/28
9	1931	2377737	US-PGPUB;	11:08
	1			11.00
			EPO; JPO;	
			DERWENT;	
1.0	3540	257/720	IBM_TDB	2002/06/22
10	1543	257/738	USPAT;	2002/06/28
			US-PGPUB;	11:08
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
11	1641	257/784	USPAT;	2002/06/28
			US-PGPUB;	11:08
			EPO; JPO;	[
			DERWENT;	!
			IBM TDB	
12	1783	257/786	USPAT;	2002/06/28
			US-PGPUB;	11:08
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
13	2602195	((integrated adj circuit) ic	USPAT;	2002/06/28
10	2002193	semiconductor die chip dice) (flipchip	US-PGPUB;	11:09
		(flip adj chip) bumps balls standoff)	EPO; JPO;	1
•		(III) adj chip) bamps balls standoll)	DERWENT;	
			IBM_TDB	

14	8954	257/686 257/685 257/723 257/777 257/778	USPAT; 2002/06/28
		257/737 257/738 257/784 257/786	US-PGPUB; 11:09
			EPO; JPO;
		*	DERWENT;
			IBM_TDB
15	124853	438/\$7.ccls.	USPAT; 2002/06/28
			US-PGPUB;   11:09
			EPO; JPO;
			DERWENT;
			IBM_TDB
16	91119	361/\$7.ccls.	USPAT; 2002/06/28
			US-PGPUB; 11:09
	İ		EPO; JPO;
			DERWENT;
			IBM TDB
17	4715	(flipchip (flip adj chip) bumps balls	USPAT; 2002/06/28
		standoff) and (257/686 257/685 257/723	US-PGPUB; 11:14
		257/777 257/778 257/737 257/738 257/784	EPO; JPO;
		257/786)	DERWENT;
			IBM_TDB

	L	Hits	Search Text	DB	Time stamp
11:07   10   15:75   11:07   10   15:75   11:07   10   15:75   11:08					2002/06/20
2	1	2124099		·	
2			die chip dice	· ·	11:07
Simple   S					
2   579735   flipchip (flip adj chip) bumps balls   USPĀT;   CO02/06/28   11:08   USPĀT;   USPGPUB;   EPO; JPO;   DERWENT; IBM TDB   USPĀT;   USPGPUB;   EPO; JPO; JPO; DERWENT; IBM TDB   USPĀT;   USPGPUB;   EPO; JPO; JPO; JPO; JPO; JPO; JPO; JPO; J					
Standoff   Standoff   SPO, JPO; DERWENT; IBM TDB   STATE   SPO, JPO; DERWENT; IBM TDB   SPAT; US-ECPUB; EPO; JPO; JPO; DERWENT; IBM TDB   SPAT; US-ECPUB; EPO; JPO; JPO; JPO; JPO; JPO; JPO; JPO; J					(0.5 (0.5
257/686   257/686   257/686   257/6856   2	2	579735			1
1575   257/686   DERWINT;   IM TIDE USPAT;   US-PGPUB;   EPO; JPO; DERWINT;   IN TIDE USPAT;   US-PGPUB;   EPO; JPO; DERWINT;   IBM TIDE USPAT;   US-PGPUB;   EPO; JPO; JPO; JPO; JPO; JPO; JPO; JPO; J			standoff	·	11:08
18M TDB   18M					
1575   257/686   USPĀT;   2002/06/28   11:08					
11:08					
1	3	1575	257/686	· ·	
13   2602195   257/885   DERWENT; ISM TIDE   2002/06/28   11:08   2002					11:08
1					
4 0 257/6856					
11:08     10:08     10:08     10:08     10:08     10:08       10:08     10					
Second   S	4	0	257/6856		
DERMENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;					11:08
TIME TOB   USPAT: US-PGPUB; EPO; JPO; DERWENT: IBM TOB USPAT: US-PGPUB; EPO; JPO; DERWENT: IBM TOB USPAT: US-PGPUB; EPO; JPO; DERWENT: IBM TOB USPAT: US-PGPUB; EPO; JPO; DERWENT: IBM TOB USPAT: US-PGPUB; EPO; JPO; DERWENT: IBM TOB USPAT: US-PGPUB; EPO; JPO; DERWENT: IBM TOB USPAT: USPAT				EPO; JPO;	
2002/06/28   11:08   2002/06/28   11:08   2002/06/28   11:08   2002/06/28   11:08   2002/06/28				1	
US-PGPUB;   EPO; JPO; DRWENT; IBM TDB   USPAT; US-PGPUB;   EPO; JPO; DERWENT; IBM TDB   USPAT; US-PGPUB;   USPAT; US-PGPUB;					
SPO; JPO; DERWENT; IBM TDB USPAT; US-FGPUB; EFO; JPO; DERWENT; US-FG	5	734	257/685		1
DERWENT;   IBM TDB   USPAT;   US-PGPUB;   EPO; JPO;   DERWENT;   US-PGPUB;   US-PGPUB				1	11:08
18M TDB   1902/06/28   11:08				EPO; JPO;	i
2481   257/723   USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; EPO; JPO; DERW				DERWENT;	
US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; ISM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT; US-PGP				IBM_TDB	
1398   257/777   1398   257/777   1398   257/777   1398   257/777   1398   257/778   1398   11:08   10   1543   257/784   257/784   257/784   257/784   257/784   257/784   257/784   257/784   257/786   25	6	2481	257/723	USPAT;	2002/06/28
7 1398 257/777 USPAT; IBM_TDB USPAT;				US-PGPUB;	11:08
TIM TDB				EPO; JPO;	
7				DERWENT;	
US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; J				IBM_TDB	
8 2304 257/778   EPO; JPO; DERWENT; IBM TDB USPĀT; US-FGPUB; EPO; JPO; DERWENT; EPO; JPO; DERWENT; US-FGPUB; EPO; JPO; DERWENT; EPO; JPO;	7	1398	257/777	USPAT;	2002/06/28
DERWENT;   IBM_TDB   USPAT;   US-PGPUB;   EPO; JPO;   DERWENT;   IBM_TDB   USPAT;				US-PGPUB;	11:08
BM_TDB   USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB   USPAT; US-P				EPO; JPO;	
8 2304 257/778 USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT;				DERWENT;	
1931   257/737   US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; III.09				IBM_TDB	
Pop	8	2304	257/778	USPAT;	2002/06/28
DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;				US-PGPUB;	11:08
9 1931 257/737				EPO; JPO;	
9 1931 257/737 USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT;				DERWENT;	
US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT;				IBM_TDB	
EPO; JPO; DERWENT; IBM_TDB   USPAT; US-PGPUB; US-PGPUB	9	1931	257/737		
DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; ISM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; ISM_TDB USPAT; ISM_TDB				1	11:08
1543   257/738   IBM_TDB   USPAT;   USPGPUB;   EPO; JPO;   DERWENT;   IBM_TDB   USPAT;   USPGPUB;   EPO; JPO;   DERWENT;   IBM_TDB   USPAT;   USP					
10		,			
US-PGPUB; EPO; JPO; DERWENT; IBM TDB US-PGPUB; EPO; JPO; DERWENT;					
11	10	1543	257/738		
DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT;				US-PGPUB;	11:08
18M_TDB					
11 1641 257/784 USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPĀT; USPĀPUB; EPO; JPO; DERWENT;				DERWENT;	
US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT;					
US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; USPAPUB; EPO; JPO; DERWENT;	11	1641	257/784	USPAT;	
DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; USPAPUB; EPO; JPO; DERWENT;				US-PGPUB;	11:08
12 1783 257/786 IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US				EPO; JPO;	
12 1783 257/786 USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; Semiconductor die chip dice) (flipchip (flip adj chip) bumps balls standoff) US-PGPUB; EPO; JPO; DERWENT;					
US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; Semiconductor die chip dice) (flipchip (flip adj chip) bumps balls standoff) US-PGPUB; EPO; JPO; DERWENT;					
US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; Semiconductor die chip dice) (flipchip (flip adj chip) bumps balls standoff) US-PGPUB; EPO; JPO; DERWENT;	12	1783	257/786		2002/06/28
2602195 ((integrated adj circuit) ic semiconductor die chip dice) (flipchip (flip adj chip) bumps balls standoff)  EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;					11:08
2602195 ((integrated adj circuit) ic semiconductor die chip dice) (flipchip (flip adj chip) bumps balls standoff)  DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;				EPO; JPO;	
2602195 ((integrated adj circuit) ic semiconductor die chip dice) (flipchip (flip adj chip) bumps balls standoff)  IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;					
2602195 ((integrated adj circuit) ic semiconductor die chip dice) (flipchip (flip adj chip) bumps balls standoff)  USPĀT; US-PGPUB; EPO; JPO; DERWENT;					
semiconductor die chip dice) (flipchip US-PGPUB; [11:09] (flip adj chip) bumps balls standoff) EPO; JPO; DERWENT;	13	2602195	((integrated adj circuit) ic		2002/06/28
(flip adj chip) bumps balls standoff)		-332233	semiconductor die chip dice) (flipchip		
DERWENT;	1		(flip adj chip) bumps balls standoff)	1	
	1		,		
				IBM TDB	

14	8954	257/686 257/685 257/723 257/777 257/778	USPAT;	2002/06/28
		257/737 257/738 257/784 257/786	US-PGPUB;	11:09
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
15	124853	438/\$7.ccls.	USPAT;	2002/06/28
			US-PGPUB;	11:09
	1		EPO; JPO;	
			DERWENT;	
			IBM_TDB	
16	91119	361/\$7.ccls.	USPAT;	2002/06/28
			US-PGPUB;	11:09
			EPO; JPO;	
İ			DERWENT;	
			IBM_TDB	
17	4715		USPAT;	2002/06/28
		standoff) and (257/686 257/685 257/723	US-PGPUB;	11:14
		257/777 257/778 257/737 257/738 257/784	EPO; JPO;	
		257/786)	DERWENT;	
	1		IBM_TDB	